

Diagram illustrating the cross-section of a 1.5 μm CMOS process. The diagram shows the substrate, gate oxide, gate, channel, and contact regions. Dimensions are given in microns:

- Gate width: 75
- Channel width: 63
- Contact width: 97
- Gate oxide thickness: 292
- Channel oxide thickness: 98
- Chip thickness: 125

- IDEAL FOR HIGH DYNAMIC RANGE RECEIVER APPLICATIONS
- 1.6 dB NOISE FIGURE AT 12 GHz
- +24.5 dBm OUTPUT POWER AT 12 GHz
- 9 dB SMALL SIGNAL GAIN AT 12 GHz
- 0.3 MICRON REFRACTORY METAL/GOLD GATE
- 750 MICRON GATE WIDTH
- AVAILABLE IN CHIP AND PACKAGES

The MwT-A9 is a GaAs MESFET device whose nominal quarter-micron gate length and 750 micron gate width make it ideally suited to applications requiring high-gain in the 500 MHz to 18 GHz frequency range with moderate power output while exhibiting low noise figure. The chip is produced using MWT's reliable metal system and devices from each wafer are screened to insure reliability. All chips are passivated using MWT's patented "Diamond-Like Carbon" process for increased durability. Designers can use MWT's unique BIN selection feature to choose devices from narrow Idss ranges, insuring consistent circuit operation.

SYMBOL	PARAM. & CONDITIONS	UNITS	MIN	TYP	MAX
IDSS	Saturated Drain Current V _{ds} = 4.0 V V _{GS} = 0.0 V	mA	78		282
G _m	Transconductance V _{ds} = 2.0 V V _{GS} = 0.0 V	mS	95	120	
V _p	Pinch-off Voltage V _{ds} = 3.0 V ID = 5.0 mA	V		-2.0	-5.0
BV _{GSO}	Gate-to-Source Breakdown Volt. I _{gs} = -1.0 mA	V	-5.0		-10.0
BV _{GDO}	Gate-to-Drain Breakdown Volt. I _{gd} = -1.0 mA	V	-6.0		-10.0
R _{th}	Thermal	MwT-A9 Chip, A971	°C/W		70
	Resistance	MwT-A970, A973			175*
	*Overall R _{th} depends on case mounting.				

SYMBOL	PARAMETERS AND CONDITIONS	FREQ	UNITS	MIN	TYP
PLdB	Output Power at 1 dB Compression VDS= 5.0 V IDS= 0.6 IDS=120mA	12 GHz	dBm	23.0	24.5
SSG	Small Signal Gain VDS= 5.0 V IDS= 0.6 IDS=120mA	12 GHz	dB	8.5	9.0
NFopt	Optimum Noise Figure VDS= 3.0 V IDS= 30mA	12 GHz	dB		1.8
GA	Gain at Optimum Noise Figure VDS= 3.0 V IDS= 30mA	12 GHz	dB	6.0	6.5

The diagram shows a small-signal equivalent circuit for a common-source MOSFET amplifier. The input is labeled 'GATE' and the output is labeled 'DRAIN'. The circuit includes the following components:

- Input side:** Inductor L_g in series with the gate; capacitor C_{pg} in parallel with the gate to ground.
- Gate region:** Resistor R_g in series with the gate; capacitor C_{gs} in parallel with the gate to source.
- Channel region:** A dependent current source labeled $gm \tau$ in parallel with resistor R_{ds} . Resistor R_i is in parallel with the gate to the current source. Resistor R_s is in parallel with the current source to the source terminal.
- Drain region:** Resistor R_d in series with the drain; capacitor C_{ds} in parallel with the drain to source.
- Output side:** Inductor L_d in series with the drain; capacitor C_{pd} in parallel with the drain to ground.
- Source:** Inductor L_s in series with the source to ground.

Source Resistance	R_s	0.80	Ω
Source Inductance	L_s	0.04	nH
Drain-Source Resistance	R_{ds}	100.0	Ω
Drain-Source Capacitance	C_{ds}	0.08	pF
Drain Resistance	R_d	1.0	Ω
Drain Pad Capacitance	C_{pd}	0.10	pF
Drain Inductance	L_d	0.28	nH
Gate Bond Wire Inductance	L_g	0.10	nH
Gate Pad Capacitance	C_{pg}	0.03	pF
Gate Resistance	R_g	0.50	Ω
Gate-Source Capacitance	C_{gs}	0.78	pF
Channel Resistance	R_i	0.8	Ω
Gate-Drain Capacitance	C_{gd}	0.10	pF
Transconductance	g_m	120.0	mS
Transit Time	τ	1.0	psec

Chip	MwT-A9
Package 70	MwT-A970
Package 71	MwT-A971
Package 73	MwT-A973

For Package information, please see supplementary application note from our website at www.mwtinc.com. When placing an order or inquiry, please specify BIN range, wafer no. if known, and screening level required.

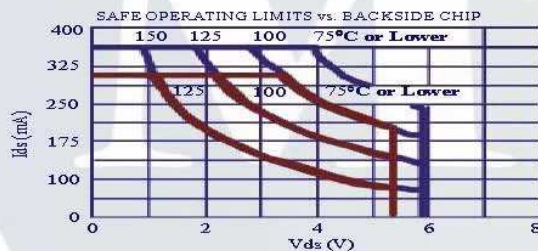
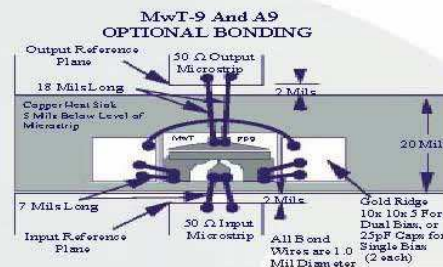
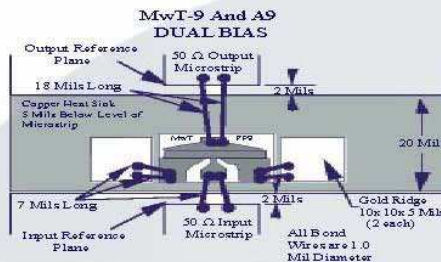
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MwT-A9

18 GHz High Gain, Low Noise

GaAs FET



— Absolute Maximum — Continuous Maximum

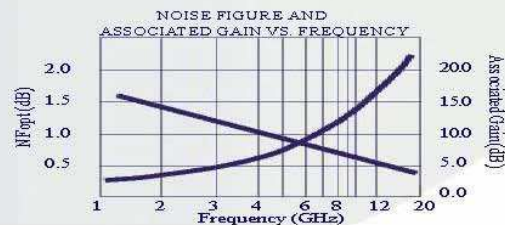
MAXIMUM RATINGS AT $T_a = 25^\circ\text{C}$

SYMBOL	PARAMETER	UNITS	CONT MAX*	ABSOLUTE MAX*
VDS	Drain to Source Voltage	V	See Safe Operating Limits	
Tch	Channel Temperature	$^\circ\text{C}$	+150	+175
Tst	Storage Temperature	$^\circ\text{C}$	-65 to +150	+175
Pin	RF Input Power	mW	240	360

NOTES: 1. Exceeding any one of these limits in continuous operation may reduce the mean time-to-failure below the design goals.
2. Exceeding any one of these limits may cause permanent damage.

TYPICAL NOISE PARAMETERS
MwT-A9LN Chip: VDS= 3.0V IDS= 35mA

FREQUENCY GHz	NF MIN dB	GAMMA OPT MAG	ANGLE	Rn/50
1.00	0.30	0.85	4.5	0.19
2.00	0.33	0.69	36.8	0.18
4.00	0.62	0.56	73.4	0.19
6.00	0.93	0.52	106.3	0.19
10.00	1.48	0.37	132.0	0.17
12.00	1.73	0.61	167.3	0.17
16.00	2.19	0.68	-169.8	0.16
18.00	2.40	0.71	-160.8	0.15



Bin Selection Guide

Bin No.	A	B	C	D	E
Idss	78-	114-	150-	198-	234-
Range	114mA	150mA	198mA	234mA	294mA

BIN ACCURACY STATEMENT

When placing order or inquiring, please specify BIN range, wafer no., if known, and screening level required.

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